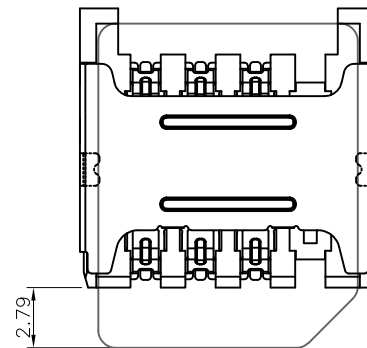
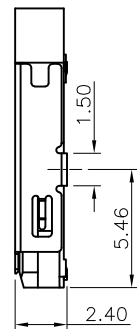
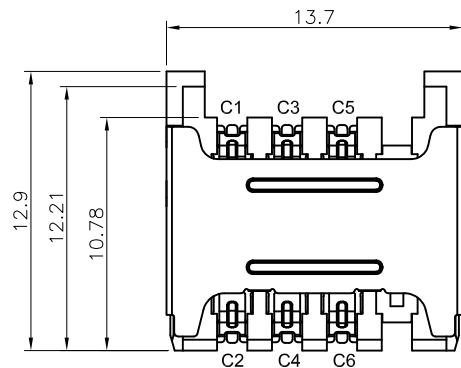
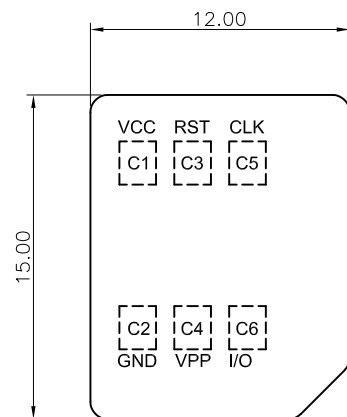
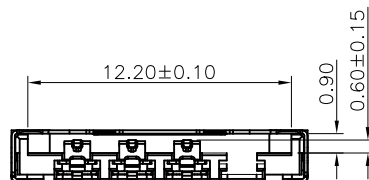
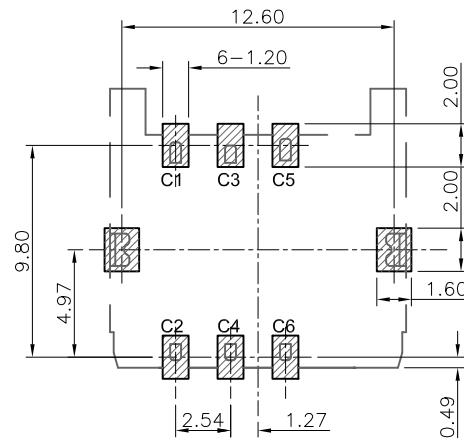




INSERT CARD



MICRO SIM CARD



RECOMMENDED P.C.B LAYOUT
TOLERANCE : ±0.05

SPECIFICATION:

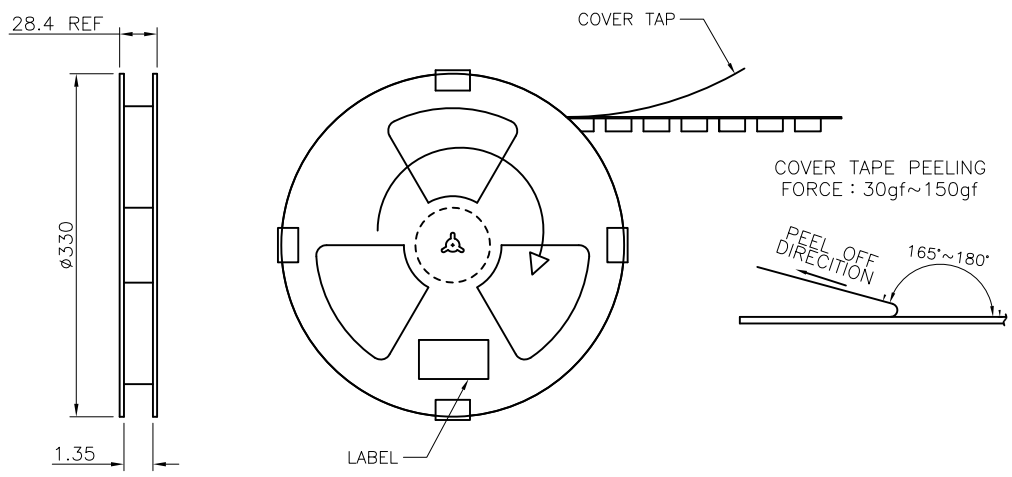
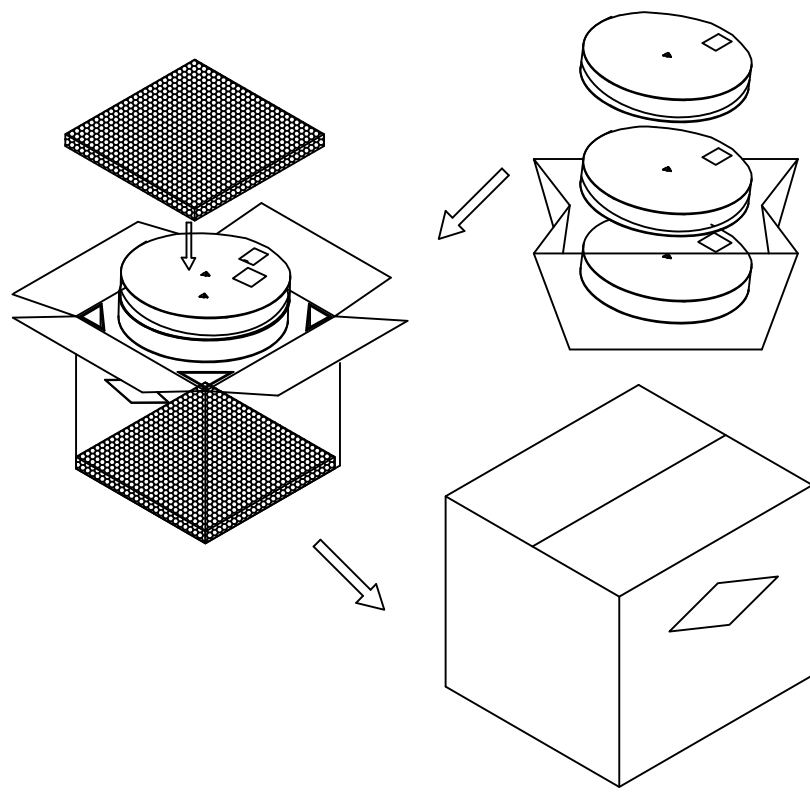
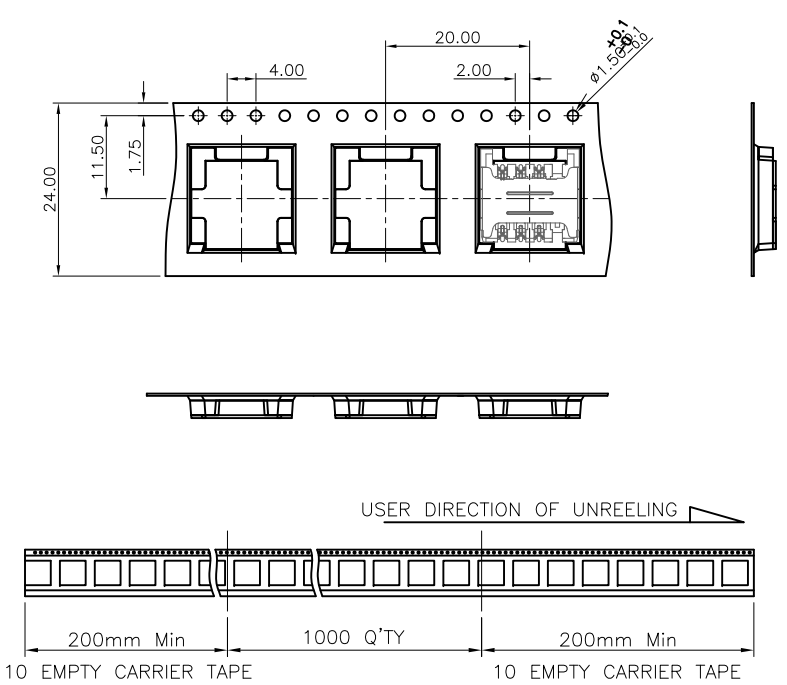
1. Current Rating: 0.5A
2. Voltage Rating: 125V AC/DC
3. Contact Resistance: 100mΩ Max.
4. Insulator Resistance: 1,000MΩ Min.
5. Durability: 5,000 Cycles
6. Operating Temperature : -40°C ~ +85°C

MICRO SIM CARD	
PIN NO.	DESCRIPTION
C1	VCC
C3	RST
C5	CLK
C2	GND
C4	VPP
C6	I/O

3.	SHELL	Stainless Steel, Gold Plating on Solder Area
2.	CONTACT	Copper Alloy , Gold Plating on Contact Area and Gold Plating on Solder Area
1.	HOUSING	Hi-Temp Thermoplastic, UL94v-0, Black
NO.	PART NAME	DESCRIPTION
DIMENSIONS : mm		TOLERANCES UNLESS OTHERWISE SPECIFIED : X. ± 0.30 X.X ± 0.20 X.XX ± 0.10 ANGLES ± 3°
SCALE 1 : 1		DWN JACK WU 20121225
SHEET 1/2		CHK PETER WANG 20121225
SIZE A4		APVD SIMON LI 20121225
CUSTOMER DRAWING		PRODUCT No. CX1-MSM6102-41
		DRAWING No. CS-MSM002

Chunxin Technology

NAME
Micro SIM Socket Push Pull Type
6Pin, H=2.45mm



NOTE :

1. CARTON SIZE : 350 x 350 x 350mm
2. 1,000 PCS / REEL
3. 10,000PCS / CARTON

NO.	PART NAME		DESCRIPTION	
DIMENSIONS : mm	TOLERANCES UNLESS OTHERWISE SPECIFIED : X. ± 0.30 X.X ± 0.20 X.XX ± 0.10 ANGLES ± 3°		Chunxin Technology NAME	
				
SCALE 1 : X	DWN JACK WU	20121225	Micro SIM Socket Push Pull Type 6Pin, H=2.45mm	
SHEET 2/2	CHK PETER WANG	20121225		
SIZE A4	APVD SIMON LI	20121225	PRODUCT No. CX1-MSM6102-41	
CUSTOMER DRAWING			DRAWING No. CS-MSM002	

1	INITIAL RELEASE	JACK WU	2012/12/25
2	NEW FORM	JACK WU	2020/05/08
3			